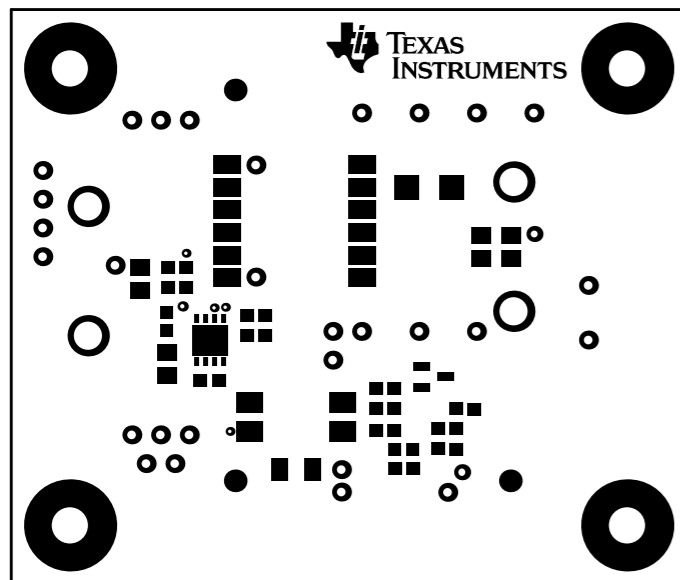
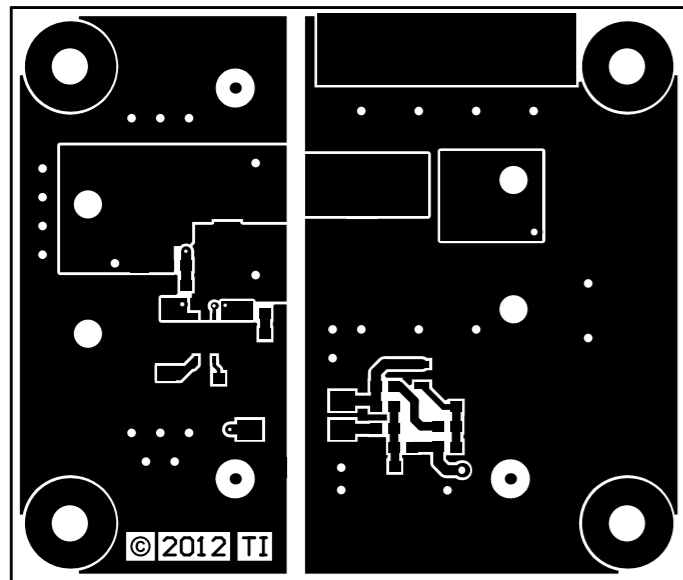


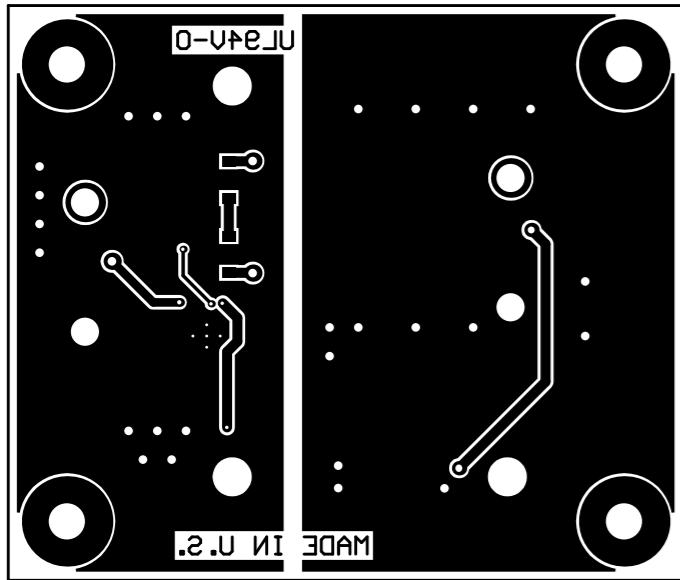
|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7902                 | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay         |                                  |                   |                                |
| PLOT NAME = Top Overlay          | GENERATED : 3/25/2015 2:00:39 PM | TEXAS INSTRUMENTS |                                |



|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7902                 | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder          |                                  |                   |                                |
| PLOT NAME = Top Solder Mask      | GENERATED : 3/25/2015 2:00:40 PM | TEXAS INSTRUMENTS |                                |

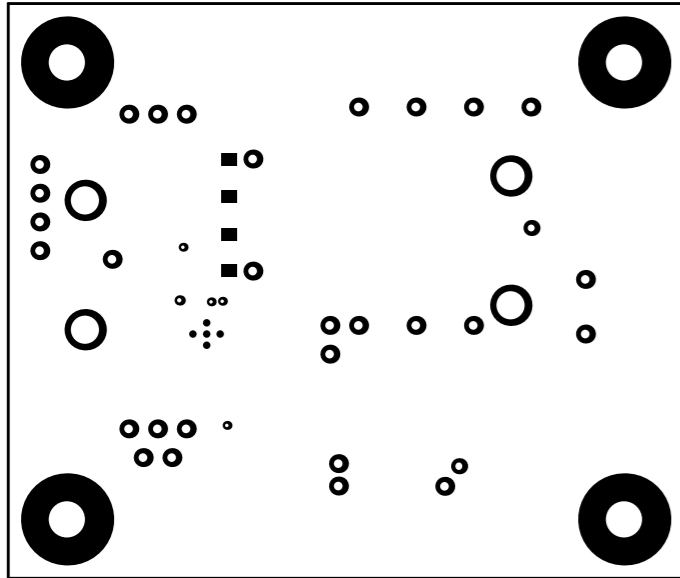


|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7902                 | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer           |                                  |                   |                                |
| PLOT NAME = Top Layer            | GENERATED : 3/25/2015 2:00:41 PM | TEXAS INSTRUMENTS |                                |

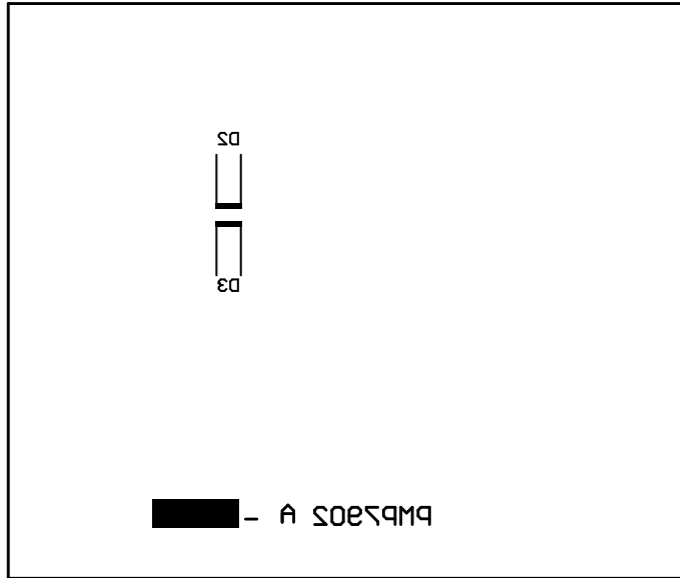


SUN: Not In VersionControl

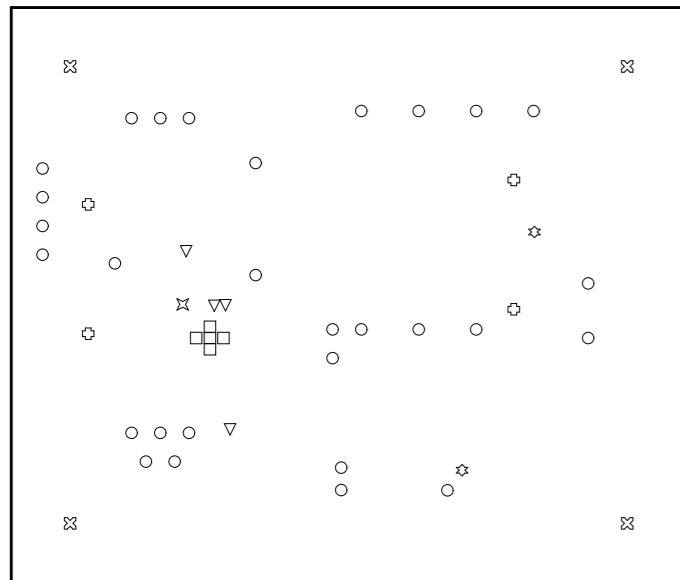
|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7902                 | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer        |                                  |                   |                                |
| PLOT NAME = Bottom Layer         | GENERATED : 3/25/2015 2:00:41 PM | TEXAS INSTRUMENTS |                                |



|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7902                 | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder       |                                  |                   |                                |
| PLOT NAME = Bottom Solder Mask   | GENERATED : 3/25/2015 2:00:42 PM | TEXAS INSTRUMENTS |                                |



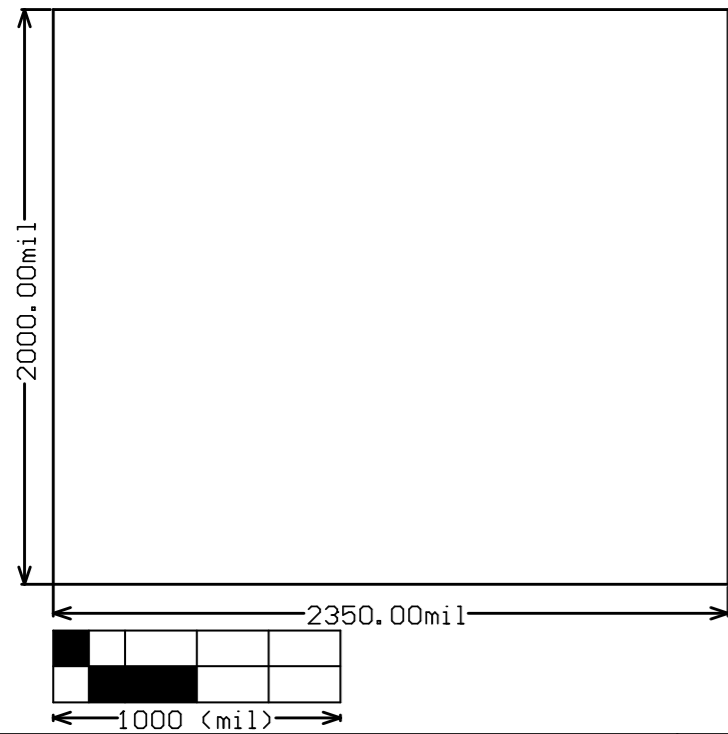
|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7902                 | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay      |                                  |                   |                                |
| PLOT NAME = Bottom Overlay       | GENERATED : 3/25/2015 2:00:43 PM | TEXAS INSTRUMENTS |                                |



| Symbol | Hit Count       | Tool Size          | Plated | Hole Type |
|--------|-----------------|--------------------|--------|-----------|
| □      | 5               | 10mil (0.254mm)    | PTH    | Round     |
| ▽      | 4               | 12mil (0.305mm)    | PTH    | Round     |
| ⊠      | 1               | 15mil (0.381mm)    | PTH    | Round     |
| ☆      | 2               | 25mil (0.635mm)    | PTH    | Round     |
| ○      | 29              | 30mil (0.762mm)    | PTH    | Round     |
| ⊕      | 4               | 98.425mil (2.5mm)  | PTH    | Round     |
| ⊗      | 4               | 125.984mil (3.2mm) | PTH    | Round     |
|        | <b>49 Total</b> |                    |        |           |

Drill Table

|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7902                 | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing       |                                  |                   |                                |
| PLOT NAME = Drill Drawing        | GENERATED : 3/25/2015 2:00:44 PM | TEXAS INSTRUMENTS |                                |



|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP7902                 | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions |                                  |                   |                                |
| PLOT NAME = Board Dimensions     | GENERATED : 3/25/2015 2:00:44 PM | TEXAS INSTRUMENTS |                                |



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